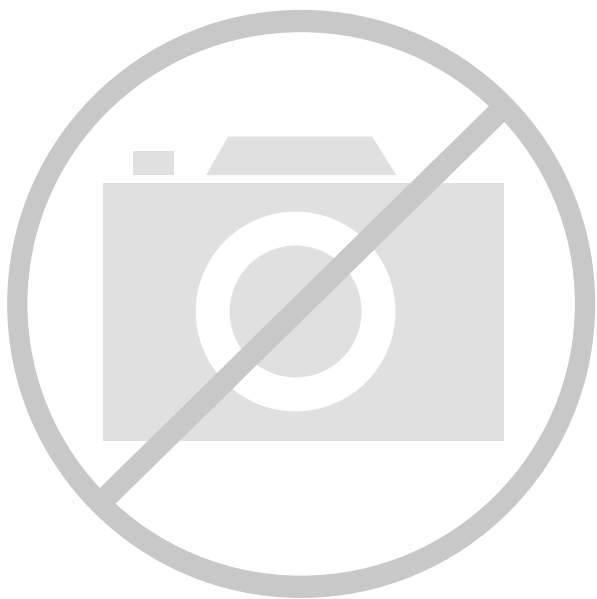




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Understanding [Embedded - FPGAs \(Field Programmable Gate Array\)](#)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details

Product Status	Obsolete
Number of LABs/CLBs	6144
Number of Logic Elements/Cells	27648
Total RAM Bits	393216
Number of I/O	660
Number of Gates	1569178
Voltage - Supply	1.71V ~ 1.89V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	1156-BBGA
Supplier Device Package	1156-FBGA (35x35)
Purchase URL	https://www.e-xfl.com/product-detail/xilinx/xcv1000e-8fg1156c

Table 1: Virtex-E Field-Programmable Gate Array Family Members

Device	System Gates	Logic Gates	CLB Array	Logic Cells	Differential I/O Pairs	User I/O	BlockRAM Bits	Distributed RAM Bits
XCV50E	71,693	20,736	16 x 24	1,728	83	176	65,536	24,576
XCV100E	128,236	32,400	20 x 30	2,700	83	196	81,920	38,400
XCV200E	306,393	63,504	28 x 42	5,292	119	284	114,688	75,264
XCV300E	411,955	82,944	32 x 48	6,912	137	316	131,072	98,304
XCV400E	569,952	129,600	40 x 60	10,800	183	404	163,840	153,600
XCV600E	985,882	186,624	48 x 72	15,552	247	512	294,912	221,184
XCV1000E	1,569,178	331,776	64 x 96	27,648	281	660	393,216	393,216
XCV1600E	2,188,742	419,904	72 x 108	34,992	344	724	589,824	497,664
XCV2000E	2,541,952	518,400	80 x 120	43,200	344	804	655,360	614,400
XCV2600E	3,263,755	685,584	92 x 138	57,132	344	804	753,664	812,544
XCV3200E	4,074,387	876,096	104 x 156	73,008	344	804	851,968	1,038,336

Virtex-E Compared to Virtex Devices

The Virtex-E family offers up to 43,200 logic cells in devices up to 30% faster than the Virtex family.

I/O performance is increased to 622 Mb/s using Source Synchronous data transmission architectures and synchronous system performance up to 240 MHz using singled-ended SelectI/O technology. Additional I/O standards are supported, notably LVPECL, LVDS, and BLVDS, which use two pins per signal. Almost all signal pins can be used for these new standards.

Virtex-E devices have up to 640 Kb of faster (250 MHz) block SelectRAM, but the individual RAMs are the same size and structure as in the Virtex family. They also have eight DLLs instead of the four in Virtex devices. Each individual DLL is slightly improved with easier clock mirroring and 4x frequency multiplication.

V_{CCINT} , the supply voltage for the internal logic and memory, is 1.8 V, instead of 2.5 V for Virtex devices. Advanced processing and 0.18 μ m design rules have resulted in smaller dice, faster speed, and lower power consumption.

I/O pins are 3 V tolerant, and can be 5 V tolerant with an external 100 Ω resistor. PCI 5 V is not supported. With the addition of appropriate external resistors, any pin can tolerate any voltage desired.

Banking rules are different. With Virtex devices, all input buffers are powered by V_{CCINT} . With Virtex-E devices, the LVTTTL, LVCMOS2, and PCI input buffers are powered by the I/O supply voltage V_{CCO} .

The Virtex-E family is not bitstream-compatible with the Virtex family, but Virtex designs can be compiled into equivalent Virtex-E devices.

The same device in the same package for the Virtex-E and Virtex families are pin-compatible with some minor exceptions. See the data sheet pinout section for details.

General Description

The Virtex-E FPGA family delivers high-performance, high-capacity programmable logic solutions. Dramatic increases in silicon efficiency result from optimizing the new architecture for place-and-route efficiency and exploiting an aggressive 6-layer metal 0.18 μ m CMOS process. These advances make Virtex-E FPGAs powerful and flexible alternatives to mask-programmed gate arrays. The Virtex-E family includes the nine members in Table 1.

Building on experience gained from Virtex FPGAs, the Virtex-E family is an evolutionary step forward in programmable logic design. Combining a wide variety of programmable system features, a rich hierarchy of fast, flexible interconnect resources, and advanced process technology, the Virtex-E family delivers a high-speed and high-capacity programmable logic solution that enhances design flexibility while reducing time-to-market.

Virtex-E Architecture

Virtex-E devices feature a flexible, regular architecture that comprises an array of configurable logic blocks (CLBs) surrounded by programmable input/output blocks (IOBs), all interconnected by a rich hierarchy of fast, versatile routing

Architectural Description

Virtex-E Array

The Virtex-E user-programmable gate array, shown in **Figure 1**, comprises two major configurable elements: configurable logic blocks (CLBs) and input/output blocks (IOBs).

- CLBs provide the functional elements for constructing logic
- IOBs provide the interface between the package pins and the CLBs

CLBs interconnect through a general routing matrix (GRM). The GRM comprises an array of routing switches located at the intersections of horizontal and vertical routing channels. Each CLB nests into a VersaBlock™ that also provides local routing resources to connect the CLB to the GRM.

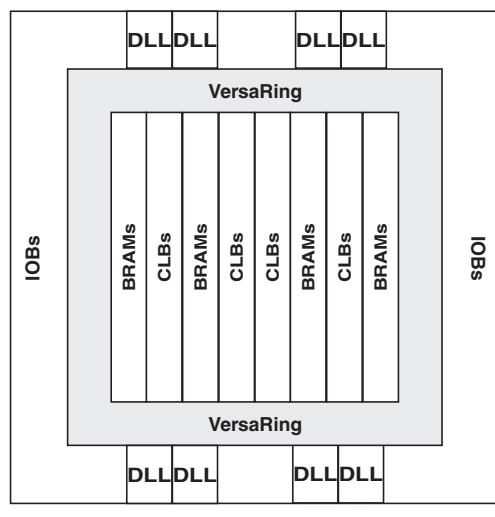


Figure 1: Virtex-E Architecture Overview

The VersaRing™ I/O interface provides additional routing resources around the periphery of the device. This routing improves I/O routability and facilitates pin locking.

The Virtex-E architecture also includes the following circuits that connect to the GRM.

- Dedicated block memories of 4096 bits each
- Clock DLLs for clock-distribution delay compensation and clock domain control
- 3-State buffers (BUFTs) associated with each CLB that drive dedicated segmentable horizontal routing resources

Values stored in static memory cells control the configurable logic elements and interconnect resources. These values load into the memory cells on power-up, and can reload if necessary to change the function of the device.

Input/Output Block

The Virtex-E IOB, **Figure 2**, features SelectI/O+ inputs and outputs that support a wide variety of I/O signalling standards, see **Table 1**.

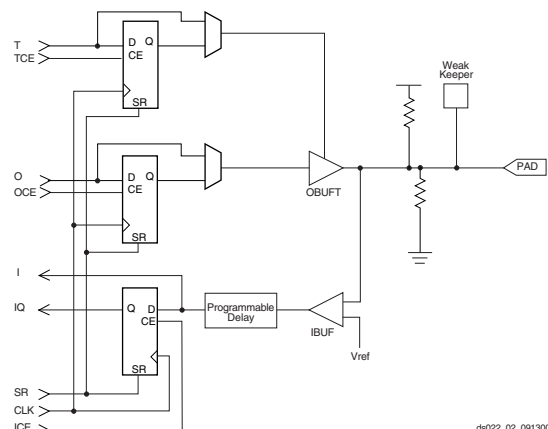


Figure 2: Virtex-E Input/Output Block (IOB)

The three IOB storage elements function either as edge-triggered D-type flip-flops or as level-sensitive latches. Each IOB has a clock signal (CLK) shared by the three flip-flops and independent clock enable signals for each flip-flop.

Dedicated Routing

Some classes of signal require dedicated routing resources to maximize performance. In the Virtex-E architecture, dedicated routing resources are provided for two classes of signal.

- Horizontal routing resources are provided for on-chip 3-state buses. Four partitionable bus lines are provided per CLB row, permitting multiple buses within a row, as shown in Figure 8.
- Two dedicated nets per CLB propagate carry signals vertically to the adjacent CLB. Global Clock Distribution Network
- DLL Location

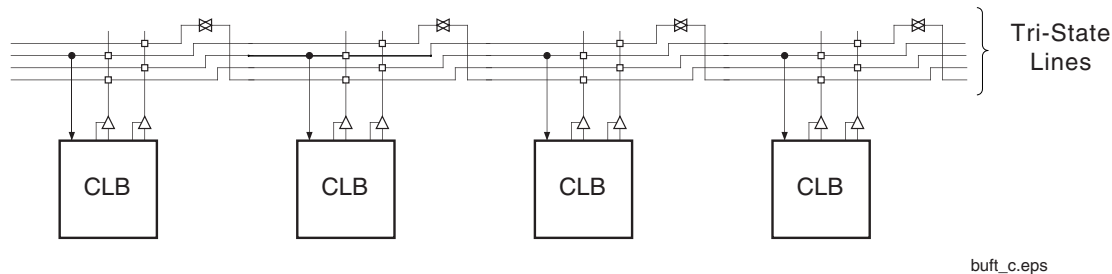


Figure 8: BUFT Connections to Dedicated Horizontal Bus Lines

Global Clock Distribution

Virtex-E provides high-speed, low-skew clock distribution through the global routing resources described above. A typical clock distribution net is shown in Figure 9.

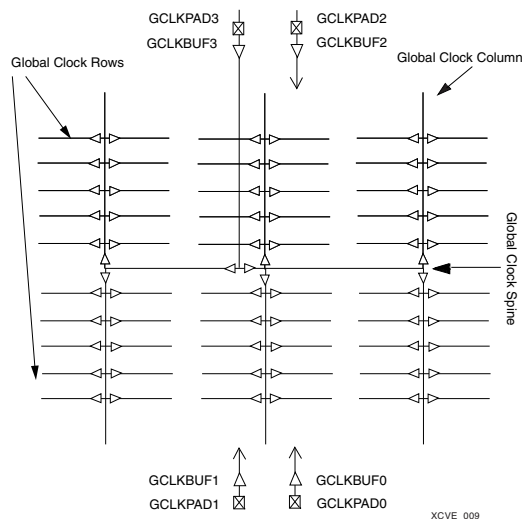


Figure 9: Global Clock Distribution Network

Clock Routing

Clock Routing resources distribute clocks and other signals with very high fanout throughout the device. Virtex-E devices include two tiers of clock routing resources referred to as global and local clock routing resources.

- The global routing resources are four dedicated global nets with dedicated input pins that are designed to distribute high-fanout clock signals with minimal skew. Each global clock net can drive all CLB, IOB, and block RAM clock pins. The global nets can be driven only by global buffers. There are four global buffers, one for each global net.
- The local clock routing resources consist of 24 backbone lines, 12 across the top of the chip and 12 across bottom. From these lines, up to 12 unique signals per column can be distributed via the 12 longlines in the column. These local resources are more flexible than the global resources since they are not restricted to routing only to clock pins.

Four global buffers are provided, two at the top center of the device and two at the bottom center. These drive the four global nets that in turn drive any clock pin.

Four dedicated clock pads are provided, one adjacent to each of the global buffers. The input to the global buffer is selected either from these pads or from signals in the general purpose routing.

Digital Delay-Locked Loops

There are eight DLLs (Delay-Locked Loops) per device, with four located at the top and four at the bottom, Figure 10. The DLLs can be used to eliminate skew between the clock input pad and the internal clock input pins throughout the device. Each DLL can drive two global clock networks. The DLL monitors the input clock and the distributed clock, and automatically adjusts a clock delay element. Additional delay is introduced such that clock edges arrive at internal flip-flops synchronized with clock edges arriving at the input.

In addition to eliminating clock-distribution delay, the DLL provides advanced control of multiple clock domains. The DLL provides four quadrature phases of the source clock, and can double the clock or divide the clock by 1.5, 2, 2.5, 3, 4, 5, 8, or 16.

ground. As the DLL delay taps reset to zero, glitches can occur on the DLL clock output pins. Activation of the RST pin can also severely affect the duty cycle of the clock output pins. Furthermore, the DLL output clocks no longer deskew with respect to one another. For these reasons, rarely use the reset pin unless re-configuring the device or changing the input frequency.

2x Clock Output — CLK2X

The output pin CLK2X provides a frequency-doubled clock with an automatic 50/50 duty-cycle correction. Until the CLKDLL has achieved lock, the CLK2X output appears as a 1x version of the input clock with a 25/75 duty cycle. This behavior allows the DLL to lock on the correct edge with respect to source clock. This pin is not available on the CLKDLLHF primitive.

Clock Divide Output — CLKDV

The clock divide output pin CLKDV provides a lower frequency version of the source clock. The CLKDV_DIVIDE property controls CLKDV such that the source clock is divided by N where N is either 1.5, 2, 2.5, 3, 4, 5, 8, or 16.

This feature provides automatic duty cycle correction such that the CLKDV output pin always has a 50/50 duty cycle, with the exception of noninteger divides in HF mode, where the duty cycle is 1/3 for N=1.5 and 2/5 for N=2.5.

1x Clock Outputs — CLK[0/90/180/270]

The 1x clock output pin CLK0 represents a delay-compensated version of the source clock (CLKIN) signal. The CLKDLL primitive provides three phase-shifted versions of the CLK0 signal while CLKDLLHF provides only the 180 phase-shifted version. The relationship between phase shift and the corresponding period shift appears in Table 13.

Table 13: Relationship of Phase-Shifted Output Clock to Period Shift

Phase (degrees)	Period Shift (percent)
0	0%
90	25%
180	50%
270	75%

The timing diagrams in Figure 25 illustrate the DLL clock output characteristics.

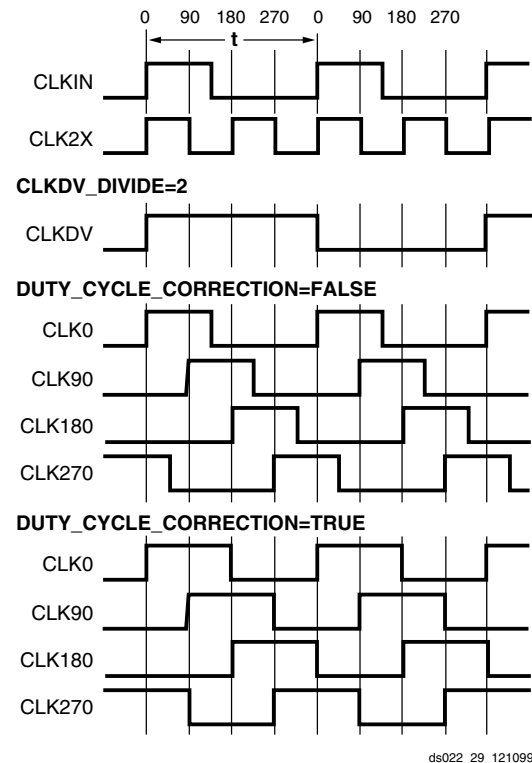


Figure 25: DLL Output Characteristics

The DLL provides duty cycle correction on all 1x clock outputs such that all 1x clock outputs by default have a 50/50 duty cycle. The DUTY_CYCLE_CORRECTION property (TRUE by default), controls this feature. In order to deactivate the DLL duty cycle correction, attach the DUTY_CYCLE_CORRECTION=FALSE property to the DLL symbol. When duty cycle correction deactivates, the output clock has the same duty cycle as the source clock.

The DLL clock outputs can drive an OBUF, a BUFG, or they can route directly to destination clock pins. The DLL clock outputs can only drive the BUFGs that reside on the same edge (top or bottom).

Locked Output — LOCKED

To achieve lock, the DLL might need to sample several thousand clock cycles. After the DLL achieves lock, the LOCKED signal activates. The DLL timing parameter section of the data sheet provides estimates for locking times.

To guarantee that the system clock is established prior to the device “waking up,” the DLL can delay the completion of the device configuration process until after the DLL locks. The STARTUP_WAIT property activates this feature.

Until the LOCKED signal activates, the DLL output clocks are not valid and can exhibit glitches, spikes, or other spurious movement. In particular the CLK2X output appears as a 1x clock with a 25/75 duty cycle.

Because any single DLL can access only two BUFs at most, any additional output clock signals must be routed from the DLL in this example on the high speed backbone routing.

The dll_2x files in the [xapp132.zip](#) file show the VHDL and Verilog implementation of this circuit.

Virtex-E 4x Clock

Two DLLs located in the same half-edge (top-left, top-right, bottom-right, bottom-left) can be connected together, without using a BUFG between the CLKDLLs, to generate a 4x clock as shown in [Figure 30](#). Virtex-E devices, like the Virtex devices, have four clock networks that are available for internal deskewing of the clock. Each of the eight DLLs have access to two of the four clock networks. Although all the DLLs can be used for internal deskewing, the presence of two GCLKBUFs on the top and two on the bottom indicate that only two of the four DLLs on the top (and two of the four DLLs on the bottom) can be used for this purpose.

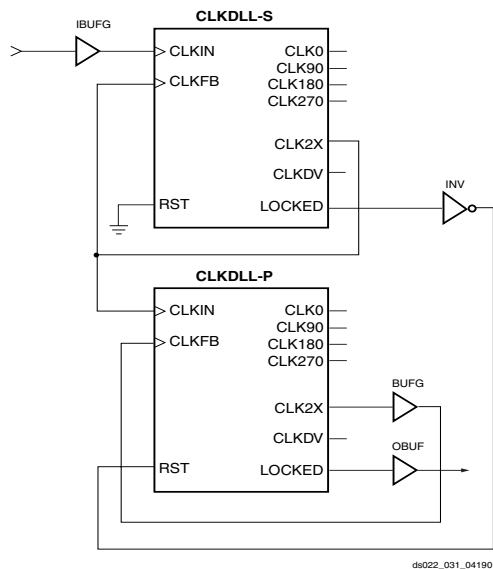


Figure 30: DLL Generation of 4x Clock in Virtex-E Devices

The dll_4xe files in the xapp132.zip file show the DLL implementation in Verilog for Virtex-E devices. These files can be found at:

<ftp://ftp.xilinx.com/pub/applications/xapp/xapp132.zip>

Using Block SelectRAM+ Features

The Virtex FPGA Series provides dedicated blocks of on-chip, true dual-read/write port synchronous RAM, with 4096 memory cells. Each port of the block SelectRAM+ memory can be independently configured as a read/write port, a read port, a write port, and can be configured to a specific data width. The block SelectRAM+ memory offers

new capabilities allowing the FPGA designer to simplify designs.

Operating Modes

Virtex-E block SelectRAM+ memory supports two operating modes:

- Read Through
- Write Back

Read Through (one clock edge)

The read address is registered on the read port clock edge and data appears on the output after the RAM access time. Some memories might place the latch/register at the outputs, depending on whether a faster clock-to-out versus set-up time is desired. This is generally considered to be an inferior solution, since it changes the read operation to an asynchronous function with the possibility of missing an address/control line transition during the generation of the read pulse clock.

Write Back (one clock edge)

The write address is registered on the write port clock edge and the data input is written to the memory and mirrored on the output.

Block SelectRAM+ Characteristics

- All inputs are registered with the port clock and have a set-up to clock timing specification.
- All outputs have a read through or write back function depending on the state of the port WE pin. The outputs relative to the port clock are available after the clock-to-out timing specification.
- The block SelectRAMs are true SRAM memories and do not have a combinatorial path from the address to the output. The LUT SelectRAM+ cells in the CLBs are still available with this function.
- The ports are completely independent from each other (i.e., clocking, control, address, read/write function, and data width) without arbitration.
- A write operation requires only one clock edge.
- A read operation requires only one clock edge.

The output ports are latched with a self timed circuit to guarantee a glitch free read. The state of the output port does not change until the port executes another read or write operation.

Library Primitives

[Figure 31](#) and [Figure 32](#) show the two generic library block SelectRAM+ primitives. [Table 14](#) describes all of the available primitives for synthesis and simulation.

IOB Output Switching Characteristics, Figure 1

Output delays terminating at a pad are specified for LVTTTL with 12 mA drive and fast slew rate. For other standards, adjust the delays with the values shown in **IOB Output Switching Characteristics Standard Adjustments**, page 10.

		Speed Grade ⁽¹⁾				Units
Description ⁽²⁾	Symbol	Min	-8	-7	-6	
Propagation Delays						
O input to Pad	T _{ILOOP}	1.04	2.5	2.7	2.9	ns, max
O input to Pad via transparent latch	T _{IOOLP}	1.24	2.9	3.1	3.4	ns, max
3-State Delays						
T input to Pad high-impedance (Note 2)	T _{IOTHZ}	0.73	1.5	1.7	1.9	ns, max
T input to valid data on Pad	T _{IOTON}	1.13	2.7	2.9	3.1	ns, max
T input to Pad high-impedance via transparent latch (Note 2)	T _{IOTLPHZ}	0.86	1.8	2.0	2.2	ns, max
T input to valid data on Pad via transparent latch	T _{IOTLPON}	1.26	3.0	3.2	3.4	ns, max
GTS to Pad high impedance (Note 2)	T _{GTS}	1.94	4.1	4.6	4.9	ns, max
Sequential Delays						
Clock CLK						
Minimum Pulse Width, High	T _{CH}	0.56	1.2	1.3	1.4	ns, min
Minimum Pulse Width, Low	T _{CL}	0.56	1.2	1.3	1.4	ns, min
Clock CLK to Pad	T _{IOCKP}	0.97	2.4	2.8	2.9	ns, max
Clock CLK to Pad high-impedance (synchronous) (Note 2)	T _{IOCKHZ}	0.77	1.6	2.0	2.2	ns, max
Clock CLK to valid data on Pad (synchronous)	T _{IOCKON}	1.17	2.8	3.2	3.4	ns, max
Setup and Hold Times before/after Clock CLK						
O input	T _{IOOCK} / T _{IOCKO}	0.43 / 0	0.9 / 0	1.0 / 0	1.1 / 0	ns, min
OCE input	T _{IOOCECK} / T _{IOCKOCE}	0.28 / 0	0.55 / 0.01	0.7 / 0	0.7 / 0	ns, min
SR input (OFF)	T _{IOSRCKO} / T _{IOCKOSR}	0.40 / 0	0.8 / 0	0.9 / 0	1.0 / 0	ns, min
3-State Setup Times, T input	T _{IOTCK} / T _{IOCKT}	0.26 / 0	0.51 / 0	0.6 / 0	0.7 / 0	ns, min
3-State Setup Times, TCE input	T _{IOTCECK} / T _{IOCKTCE}	0.30 / 0	0.6 / 0	0.7 / 0	0.8 / 0	ns, min
3-State Setup Times, SR input (TFF)	T _{IOSRCKT} / T _{IOCKTSR}	0.38 / 0	0.8 / 0	0.9 / 0	1.0 / 0	ns, min
Set/Reset Delays						
SR input to Pad (asynchronous)	T _{IOSRP}	1.30	3.1	3.3	3.5	ns, max
SR input to Pad high-impedance (asynchronous) (Note 2)	T _{IOSRHZ}	1.08	2.2	2.4	2.7	ns, max
SR input to valid data on Pad (asynchronous)	T _{IOSRON}	1.48	3.4	3.7	3.9	ns, max
GSR to Pad	T _{IOGSRQ}	3.88	7.6	8.5	9.7	ns, max

Notes:

1. A Zero "0" Hold Time listing indicates no hold time or a negative hold time. Negative values can not be guaranteed "best-case", but if a "0" is listed, there is no positive hold time.
2. 3-state turn-off delays should not be adjusted.

CLB Switching Characteristics

Delays originating at F/G inputs vary slightly according to the input used, see [Figure 2](#). The values listed below are worst-case. Precise values are provided by the timing analyzer.

		Speed Grade ⁽¹⁾				Units
Description	Symbol	Min	-8	-7	-6	
Combinatorial Delays						
4-input function: F/G inputs to X/Y outputs	T _{ILO}	0.19	0.40	0.42	0.47	ns, max
5-input function: F/G inputs to F5 output	T _{IF5}	0.36	0.76	0.8	0.9	ns, max
5-input function: F/G inputs to X output	T _{IF5X}	0.35	0.74	0.8	0.9	ns, max
6-input function: F/G inputs to Y output via F6 MUX	T _{IF6Y}	0.35	0.74	0.9	1.0	ns, max
6-input function: F5IN input to Y output	T _{F5INY}	0.04	0.11	0.20	0.22	ns, max
Incremental delay routing through transparent latch to XQ/YQ outputs	T _{IFNCTL}	0.27	0.63	0.7	0.8	ns, max
BY input to YB output	T _{BYYB}	0.19	0.38	0.46	0.51	ns, max
Sequential Delays						
FF Clock CLK to XQ/YQ outputs	T _{CKO}	0.34	0.78	0.9	1.0	ns, max
Latch Clock CLK to XQ/YQ outputs	T _{CKLO}	0.40	0.77	0.9	1.0	ns, max
Setup and Hold Times before/after Clock CLK						
4-input function: F/G Inputs	T _{ICK} / T _{CKI}	0.39 / 0	0.9 / 0	1.0 / 0	1.1 / 0	ns, min
5-input function: F/G inputs	T _{IF5CK} / T _{CKIF5}	0.55 / 0	1.3 / 0	1.4 / 0	1.5 / 0	ns, min
6-input function: F5IN input	T _{F5INCK} / T _{CKF5IN}	0.27 / 0	0.6 / 0	0.8 / 0	0.8 / 0	ns, min
6-input function: F/G inputs via F6 MUX	T _{IF6CK} / T _{CKIF6}	0.58 / 0	1.3 / 0	1.5 / 0	1.6 / 0	ns, min
BX/BY inputs	T _{DICK} / T _{CKDI}	0.25 / 0	0.6 / 0	0.7 / 0	0.8 / 0	ns, min
CE input	T _{CECK} / T _{CKCE}	0.28 / 0	0.55 / 0	0.7 / 0	0.7 / 0	ns, min
SR/BY inputs (synchronous)	T _{RCK} / T _{CKR}	0.24 / 0	0.46 / 0	0.52 / 0	0.6 / 0	ns, min
Clock CLK						
Minimum Pulse Width, High	T _{CH}	0.56	1.2	1.3	1.4	ns, min
Minimum Pulse Width, Low	T _{CL}	0.56	1.2	1.3	1.4	ns, min
Set/Reset						
Minimum Pulse Width, SR/BY inputs	T _{RPW}	0.94	1.9	2.1	2.4	ns, min
Delay from SR/BY inputs to XQ/YQ outputs (asynchronous)	T _{RQ}	0.39	0.8	0.9	1.0	ns, max
Toggle Frequency (MHz) (for export control)	F _{TOG}	-	416	400	357	MHz

Notes:

1. A Zero "0" Hold Time listing indicates no hold time or a negative hold time. Negative values can not be guaranteed "best-case", but if a "0" is listed, there is no positive hold time.

Table 10: BG352 — XCV100E, XCV200E, XCV300E

Bank	Pin Description	Pin #
4	IO_VREF_4_L53P_Y	AC12
4	IO_L53N_Y	AD12
4	IO_L54P	AE12
4	IO_L54N	AF12
4	IO	AD13 ¹
4	IO_LVDS_DLL_L55P	AC13
4	GCK0	AE13
5	GCK1	AF14
5	IO_LVDS_DLL_L55N	AD14
5	IO	AF15 ¹
5	IO	AE15
5	IO_L56P_Y	AD15
5	IO_VREF_5_L56N_Y	AC15
5	IO_L57P_Y	AE16
5	IO_L57N_Y	AE17
5	IO	AD16 ¹
5	IO_L58P	AC16
5	IO_L58N	AF18
5	IO	AE18 ¹
5	IO_L59P_YY	AD17
5	IO_L59N_YY	AC17
5	IO_L60P_YY	AD18
5	IO_VREF_5_L60N_YY	AC18
5	IO_L61P_Y	AF20
5	IO_L61N_Y	AE20
5	IO	AD19
5	IO	AC19 ¹
5	IO	AF21 ¹
5	IO_L62P_YY	AE21
5	IO_VREF_5_L62N_YY	AD20
5	IO_L63P_YY	AF23
5	IO_L63N_YY	AE22
5	IO	AD21 ¹

Table 10: BG352 — XCV100E, XCV200E, XCV300E

Bank	Pin Description	Pin #
5	IO_L64P_YY	AC21
5	IO_VREF_5_L64N_YY	AE23 ²
5	IO	AD22
5	IO	AF24 ¹
5	IO	AC22 ¹
6	IO_L65N_YY	AC24
6	IO_L65P_YY	AD25
6	IO	AB24 ¹
6	IO	AA23 ¹
6	IO	AC25
6	IO_VREF_6_L66N_YY	AD26 ²
6	IO_L66P_YY	AC26
6	IO	Y23 ¹
6	IO_L67N_YY	AA24
6	IO_L67P_YY	AB25
6	IO_VREF_6_L68N_Y	AA25
6	IO_L68P_Y	Y24
6	IO	Y25 ¹
6	IO	AA26 ¹
6	IO_L69N	V23
6	IO_L69P	W24
6	IO	W25
6	IO_VREF_6_L70N_Y	Y26
6	IO_L70P_Y	U23
6	IO_L71N_YY	V25
6	IO_L71P_YY	U24
6	IO	V26 ¹
6	IO_L72N	T23
6	IO_L72P	U25
6	IO	T24 ¹
6	IO_L73N_YY	T25
6	IO_L73P_YY	T26
6	IO_VREF_6_L74N_Y	R24

Table 16: FG256 Package — XCV50E, XCV100E, XCV200E, XCV300E

Bank	Pin Description	Pin #
7	IO_L74N_Y	G4
7	IO_VREF_L74P_Y	H3
7	IO_L75N_YY	G2
7	IO_L75P_YY	F5
7	IO_L76N	F4
7	IO_L76P	F1
7	IO_L77N_YY	G3
7	IO_L77P_YY	F2
7	IO_L78N_Y	E1
7	IO_VREF_L78P_Y	D1 ¹
7	IO_L79N	E4
7	IO_L79P	E2
7	IO_L80N_Y	F3
7	IO_VREF_L80P_Y	C1
7	IO_L81N_YY	D2
7	IO_L81P_YY	E3
7	IO_VREF_L82N	B1 ²
7	IO_L82P	A2
2	CCLK	D15
3	DONE	R14
NA	DXN	R4
NA	DXP	P4
NA	M0	N3
NA	M1	P2
NA	M2	R3
NA	PROGRAM	P15
NA	TCK	C4
NA	TDI	A15
2	TDO	B14
NA	TMS	D3
NA	VCCINT	C3
NA	VCCINT	C14
NA	VCCINT	D4

Table 16: FG256 Package — XCV50E, XCV100E, XCV200E, XCV300E

Bank	Pin Description	Pin #
NA	VCCINT	D13
NA	VCCINT	E5
NA	VCCINT	E12
NA	VCCINT	M5
NA	VCCINT	M12
NA	VCCINT	N4
NA	VCCINT	N13
NA	VCCINT	P3
NA	VCCINT	P14
0	VCCO	F8
0	VCCO	E8
1	VCCO	F9
1	VCCO	E9
2	VCCO	H12
2	VCCO	H11
3	VCCO	J12
3	VCCO	J11
4	VCCO	M9
4	VCCO	L9
5	VCCO	M8
5	VCCO	L8
6	VCCO	J6
6	VCCO	J5
7	VCCO	H6
7	VCCO	H5
NA	GND	T16
NA	GND	T1
NA	GND	R15
NA	GND	R2
NA	GND	L11
NA	GND	L10
NA	GND	L7
NA	GND	L6

FG456 Fine-Pitch Ball Grid Array Packages

XCV200E and XCV300E devices in FG456 fine-pitch Ball Grid Array packages have footprint compatibility. Pins labeled IO_VREF can be used as either in both devices provided in this package. If the pin is not used as V_{REF} , it can be used as general I/O. Immediately following Table 18, see Table 19 for Differential Pair information.

Table 18: FG456 — XCV200E and XCV300E

Bank	Pin Description	Pin #
0	GCK3	C11
0	IO	A2 ¹
0	IO	A3
0	IO	A6 ¹
0	IO	A10
0	IO	B5
0	IO	B9
0	IO	C5
0	IO	D8
0	IO	D10
0	IO	E11 ¹
0	IO_L0N	D5
0	IO_L0P	B3
0	IO_VREF_L1N_YY	B4
0	IO_L1P_YY	E6
0	IO_L2N	A4
0	IO_L2P	E7
0	IO_VREF_L3N_YY	C6
0	IO_L3P_YY	D6
0	IO_L4N_Y	A5
0	IO_L4P_Y	B6
0	IO_L5N_Y	D7
0	IO_L5P_Y	C7
0	IO_VREF_L6N_YY	E8
0	IO_L6P_YY	B7
0	IO_L7N_YY	A7
0	IO_L7P_YY	E9
0	IO_L8N_Y	C8
0	IO_L8P_Y	B8
0	IO_L9N_Y	D9
0	IO_L9P_Y	A8

Table 18: FG456 — XCV200E and XCV300E

Bank	Pin Description	Pin #
0	IO_L10N	C9
0	IO_L10P	E10
0	IO_VREF_L11N_YY	A9
0	IO_L11P_YY	C10
0	IO_L12N_Y	F11
0	IO_L12P_Y	B10
0	IO_LVDS_DLL_L13N	B11
1	GCK2	A11
1	IO	A12 ¹
1	IO	A14
1	IO	B16 ¹
1	IO	B19
1	IO	E13
1	IO	E15
1	IO	E16
1	IO	E17 ¹
1	IO_LVDS_DLL_L13P	D11
1	IO_L14N_Y	C12
1	IO_L14P_Y	D12
1	IO_L15N_Y	B12
1	IO_L15P_Y	A13
1	IO_L16N_YY	E12
1	IO_VREF_L16P_YY	B13
1	IO_L17N_YY	C13
1	IO_L17P_YY	D13
1	IO_L18N_Y	B14
1	IO_L18P_Y	C14
1	IO_L19N_Y	F12
1	IO_L19P_Y	A15
1	IO_L20N_YY	B15
1	IO_L20P_YY	C15
1	IO_L21N_YY	A16
1	IO_VREF_L21P_YY	E14
1	IO_L22N_Y	D14
1	IO_L22P_Y	C16
1	IO_L23N_Y	D15

Table 20: FG676 — XCV400E, XCV600E

Bank	Pin Description	Pin #
3	IO	Y26
3	IO	AB25
3	IO	AC25 ¹
3	IO	AC26
3	IO_L69P_YY	P21
3	IO_L69N_YY	P23
3	IO_L70P_Y	P22
3	IO_VREF_L70N_Y	R25
3	IO_L71P_Y	P19
3	IO_L71N_Y	P20
3	IO_L72P_YY	R21
3	IO_L72N_YY	R22
3	IO_D4_L73P_YY	R24
3	IO_VREF_L73N_YY	R23
3	IO_L74P_Y	T24
3	IO_L74N_Y	R20
3	IO_L75P_Y	T22
3	IO_L75N_Y	U24
3	IO_L76P_Y	T23
3	IO_L76N_Y	U25
3	IO_L77P_Y	T21
3	IO_L77N_Y	U20
3	IO_L78P_YY	U22
3	IO_L78N_YY	V26
3	IO_L79P_YY	T20
3	IO_D5_L79N_YY	U23
3	IO_D6_L80P_YY	V24
3	IO_VREF_L80N_YY	U21
3	IO_L81P_YY	V23
3	IO_L81N_YY	W24
3	IO_L82P_Y	V22
3	IO_VREF_L82N_Y	W26 ²
3	IO_L83P_Y	Y25
3	IO_L83N_Y	V21
3	IO_L84P_YY	V20
3	IO_L84N_YY	AA26
3	IO_L85P_YY	Y24

Table 20: FG676 — XCV400E, XCV600E

Bank	Pin Description	Pin #
3	IO_VREF_L85N_YY	W23
3	IO_L86P_Y	AA24
3	IO_L86N_Y	Y23
3	IO_L87P_Y	AB26
3	IO_L87N_Y	W21
3	IO_L88P_Y	Y22
3	IO_VREF_L88N_Y	W22
3	IO_L89P_Y	AA23
3	IO_L89N_Y	AB24
3	IO_L90P_YY	W20
3	IO_L90N_YY	AC24
3	IO_D7_L91P_YY	AB23
3	IO_INIT_L91N_YY	Y21
4	GCK0	AA14
4	IO	AC18
4	IO	AE15 ¹
4	IO	AE20
4	IO	AE23
4	IO	AF14 ¹
4	IO	AF16 ¹
4	IO	AF18 ¹
4	IO	AF21
4	IO	AF23 ¹
4	IO_L92P_YY	AC22
4	IO_L92N_YY	AD26
4	IO_L93P_Y	AD23
4	IO_L93N_Y	AA20
4	IO_L94P_YY	Y19
4	IO_L94N_YY	AC21
4	IO_VREF_L95P_YY	AD22
4	IO_L95N_YY	AB20
4	IO_L96P	AE22
4	IO_L96N	Y18
4	IO_L97P	AF22
4	IO_L97N	AA19
4	IO_VREF_L98P_YY	AD21

FG860 Fine-Pitch Ball Grid Array Package

XCV1000E, XCV1600E, and XCV2000E devices in the FG860 fine-pitch Ball Grid Array package have footprint compatibility. Pins labeled IO_VREF can be used as either in all parts unless device-dependent as indicated in the footnotes. If the pin is not used as V_{REF} , it can be used as general I/O. Immediately following Table 24, see Table 25 for Differential Pair information.

Table 24: FG860 — XCV1000E, XCV1600E, XCV2000E

Bank	Pin Description	Pin #
0	GCK3	C22
0	IO	A26
0	IO	B31
0	IO	B34
0	IO	C24
0	IO	C29
0	IO	C34
0	IO	D24
0	IO	D36
0	IO	D40
0	IO	E26
0	IO	E28
0	IO	E35
0	IO_L0N_Y	A38
0	IO_L0P_Y	D38
0	IO_L1N_Y	B37
0	IO_L1P_Y	E37
0	IO_VREF_L2N_Y	A37
0	IO_L2P_Y	C39
0	IO_L3N_Y	B36
0	IO_L3P_Y	C38
0	IO_L4N_YY	A36
0	IO_L4P_YY	B35
0	IO_VREF_L5N_YY	A35
0	IO_L5P_YY	D37
0	IO_L6N_Y	C37
0	IO_L6P_Y	A34
0	IO_L7N_Y	E36
0	IO_L7P_Y	B33
0	IO_L8N_YY	A33

Table 24: FG860 — XCV1000E, XCV1600E, XCV2000E

Bank	Pin Description	Pin #
0	IO_L8P_YY	C32
0	IO_VREF_L9N_YY	C36
0	IO_L9P_YY	B32
0	IO_L10N_Y	A32
0	IO_L10P_Y	D35
0	IO_VREF_L11N_Y	C31 ²
0	IO_L11P_Y	C35
0	IO_L12N_YY	E34
0	IO_L12P_YY	A31
0	IO_VREF_L13N_YY	D34
0	IO_L13P_YY	C30
0	IO_L14N_Y	B30
0	IO_L14P_Y	E33
0	IO_L15N_Y	A30
0	IO_L15P_Y	D33
0	IO_VREF_L16N_YY	C33
0	IO_L16P_YY	B29
0	IO_L17N_YY	E32
0	IO_L17P_YY	A29
0	IO_L18N_Y	D32
0	IO_L18P_Y	C28
0	IO_L19N_Y	E31
0	IO_L19P_Y	B28
0	IO_L20N_Y	D31
0	IO_L20P_Y	A28
0	IO_L21N_Y	D30
0	IO_L21P_Y	C27
0	IO_L22N_YY	E29
0	IO_L22P_YY	B27
0	IO_VREF_L23N_YY	D29
0	IO_L23P_YY	A27
0	IO_L24N_Y	C26
0	IO_L24P_Y	D28
0	IO_L25N_Y	B26
0	IO_L25P_Y	F27
0	IO_L26N_YY	E27
0	IO_L26P_YY	C25

Table 24: FG860 — XCV1000E, XCV1600E, XCV2000E

Bank	Pin Description	Pin #
6	IO	AJ40
6	IO	AL41
6	IO	AN38
6	IO	AN42
6	IO	AP41
6	IO	AR39
6	IO_L211N_YY	AV41
6	IO_L211P_YY	AV42
6	IO_L212N_Y	AW40
6	IO_L212P_Y	AU41
6	IO_L213N_Y	AV39
6	IO_L213P_Y	AU42
6	IO_VREF_L214N_Y	AT41
6	IO_L214P_Y	AU38
6	IO_L215N	AT42
6	IO_L215P	AV40
6	IO_L216N_Y	AR41
6	IO_L216P_Y	AU39
6	IO_VREF_L217N_Y	AR42
6	IO_L217P_Y	AU40
6	IO_L218N_YY	AT38
6	IO_L218P_YY	AP42
6	IO_L219N_Y	AN41
6	IO_L219P_Y	AT39
6	IO_L220N_Y	AT40
6	IO_L220P_Y	AM40
6	IO_VREF_L221N_YY	AR38
6	IO_L221P_YY	AM41
6	IO_L222N_YY	AM42
6	IO_L222P_YY	AR40
6	IO_VREF_L223N_Y	AL40 ²
6	IO_L223P_Y	AP38
6	IO_L224N_Y	AP39
6	IO_L224P_Y	AL42
6	IO_VREF_L225N_YY	AP40
6	IO_L225P_YY	AK40
6	IO_L226N_YY	AK41

Table 24: FG860 — XCV1000E, XCV1600E, XCV2000E

Bank	Pin Description	Pin #
6	IO_L226P_YY	AN39
6	IO_L227N_Y	AK42
6	IO_L227P_Y	AN40
6	IO_VREF_L228N_YY	AM38
6	IO_L228P_YY	AJ41
6	IO_L229N_YY	AJ42
6	IO_L229P_YY	AM39
6	IO_L230N_Y	AH40
6	IO_L230P_Y	AH41
6	IO_L231N_Y	AL38
6	IO_L231P_Y	AH42
6	IO_L232N_Y	AL39
6	IO_L232P_Y	AG41
6	IO_L233N	AK39
6	IO_L233P	AG40
6	IO_L234N_Y	AJ38
6	IO_L234P_Y	AG42
6	IO_VREF_L235N_Y	AF42
6	IO_L235P_Y	AJ39
6	IO_L236N_YY	AF41
6	IO_L236P_YY	AH38
6	IO_L237N_Y	AE42
6	IO_L237P_Y	AH39
6	IO_L238N_Y	AG38
6	IO_L238P_Y	AE41
6	IO_VREF_L239N_YY	AG39
6	IO_L239P_YY	AD42
6	IO_L240N_YY	AD40
6	IO_L240P_YY	AF39
6	IO_L241N_Y	AD41
6	IO_L241P_Y	AE38
6	IO_L242N_Y	AE39
6	IO_L242P_Y	AC40
6	IO_VREF_L243N_YY	AD38
6	IO_L243P_YY	AC41
6	IO_L244N_YY	AB42
6	IO_L244P_YY	AC38

Table 25: FG860 Differential Pin Pair Summary
XCV1000E, XCV1600E, XCV2000E

Pair	Bank	P Pin	N Pin	AO	Other Functions
52	1	D11	B15	√	VREF
53	1	C14	E11	2	-
54	1	B14	C10	2	-
55	1	E10	A13	√	VREF
56	1	C9	C13	√	-
57	1	A12	D9	1	VREF
58	1	C12	E9	1	-
59	1	D8	B12	√	VREF
60	1	E8	A11	√	-
61	1	A10	C7	5	-
62	1	B10	C6	5	-
63	1	B9	A9	√	VREF
64	1	E7	A8	√	-
65	1	C5	B8	5	-
66	1	A6	A7	1	VREF
67	1	D6	B7	1	-
68	1	C4	A5	2	-
69	1	E6	B6	√	CS
70	2	F5	D2	√	DIN, D0
71	2	E4	E2	3	-
72	2	D3	F2	1	-
73	2	E1	F4	2	VREF
74	2	G2	E3	4	-
75	2	F1	G5	2	-
76	2	G1	F3	1	VREF
77	2	G4	H1	√	-
78	2	J2	G3	2	-
79	2	H5	K2	1	-
80	2	H4	K1	√	VREF
81	2	L2	L3	√	-
82	2	L1	J5	5	VREF
83	2	J4	M3	2	-
84	2	J3	M1	√	VREF
85	2	N2	K4	√	-

Table 25: FG860 Differential Pin Pair Summary
XCV1000E, XCV1600E, XCV2000E

Pair	Bank	P Pin	N Pin	AO	Other Functions
86	2	N3	K3	2	-
87	2	L5	P2	√	D1
88	2	P3	L4	√	D2
89	2	P1	R2	3	-
90	2	M5	R3	1	-
91	2	M4	R1	2	-
92	2	N4	T2	4	-
93	2	P5	T3	2	-
94	2	P4	T1	1	VREF
95	2	U2	R4	√	-
96	2	U3	T5	2	-
97	2	T4	V2	1	-
98	2	U5	V3	√	D3
99	2	V1	V5	√	-
100	2	W2	V4	5	-
101	2	W5	W1	2	-
102	2	Y2	W4	√	VREF
103	2	Y1	Y5	√	-
104	2	AA1	Y4	2	VREF
105	2	AA4	AA2	√	-
106	3	AB3	AC4	2	VREF
107	3	AB1	AC5	√	-
108	3	AD4	AC3	√	VREF
109	3	AC1	AD5	2	-
110	3	AE4	AD3	5	-
111	3	AE5	AD2	√	-
112	3	AE1	AF5	√	VREF
113	3	AE2	AG4	1	-
114	3	AG5	AF1	2	-
115	3	AH4	AF2	√	-
116	3	AF3	AJ4	1	VREF
117	3	AG1	AJ5	2	-
118	3	AG2	AK4	4	-
119	3	AG3	AL4	2	-

Table 26: FG900 — XCV600E, XCV1000E, XCV1600E

Bank	Pin Description	Pin #
3	IO_L127P_YY	Y24
3	IO_VREF_L127N_YY	AB28
3	IO_L128P_YY	AC30
3	IO_L128N_YY	AA25
3	IO_L129P	W21
3	IO_L129N	AA24
3	IO_L130P_YY	AB26
3	IO_L130N_YY	AD30
3	IO_L131P_YY	Y22
3	IO_VREF_L131N_YY	AC27
3	IO_L132P	AD28
3	IO_L132N	AB25
3	IO_L133P_YY	AC26
3	IO_L133N_YY	AE30
3	IO_L134P_YY	AD27
3	IO_L134N_YY	AF30
3	IO_L135P	AF29
3	IO_VREF_L135N	AB24
3	IO_L136P_YY	AB23
3	IO_L136N_YY	AE28
3	IO_L137P_Y	AG30 ³
3	IO_L137N_Y	AC25 ⁴
3	IO_L138P_YY	AE26
3	IO_VREF_L138N_YY	AG29 ¹
3	IO_L139P	AH30
3	IO_L139N	AC24
3	IO_L140P	AF28 ³
3	IO_L140N	AD25 ⁴
3	IO_D7_L141P_YY	AH29
3	IO_INIT_L141N_YY	AA22
4	GCK0	AJ16
4	IO	AB19 ⁴
4	IO	AC16 ⁴
4	IO	AC19
4	IO	AD18 ⁴
4	IO	AD21 ⁴

Table 26: FG900 — XCV600E, XCV1000E, XCV1600E

Bank	Pin Description	Pin #
4	IO	AE15 ⁴
4	IO	AE18 ⁴
4	IO	AE21
4	IO	AE24 ⁵
4	IO	AF17 ⁵
4	IO	AF18 ⁵
4	IO	AJ18 ⁴
4	IO	AK18
4	IO	AK25 ⁵
4	IO	AK27 ⁴
4	IO	AH23 ⁴
4	IO	AH24 ⁵
4	IO_L142P_YY	AF27
4	IO_L142N_YY	AK28
4	IO_L143P_YY	AG26 ⁴
4	IO_L143N_YY	AH27 ³
4	IO_L144P	AD23
4	IO_L144N	AJ27
4	IO_VREF_L145P	AB21 ¹
4	IO_L145N	AF25
4	IO_L146P	AC22 ⁴
4	IO_L146N	AH26 ⁴
4	IO_L147P_YY	AA21
4	IO_L147N_YY	AG25
4	IO_VREF_L148P_YY	AJ26
4	IO_L148N_YY	AD22
4	IO_L149P	AA20
4	IO_L149N	AH25
4	IO_L150P	AC21
4	IO_L150N	AF24
4	IO_L151P_YY	AG24
4	IO_L151N_YY	AK26
4	IO_VREF_L152P_YY	AJ24
4	IO_L152N_YY	AF23
4	IO_L153P	AE23
4	IO_L153N	AB20
4	IO_L154P	AC20

Table 26: FG900 — XCV600E, XCV1000E, XCV1600E

Bank	Pin Description	Pin #
7	IO_L275N_YY	G3
7	IO_L275P_YY	E1
7	IO_L276N_YY	H6
7	IO_L276P_YY	E2
7	IO_L277N	E4
7	IO_VREF_L277P	K9
7	IO_L278N_YY	J8
7	IO_L278P_YY	F4
7	IO_L279N_Y	D1 ³
7	IO_L279P_Y	H7 ⁴
7	IO_L280N_YY	G6
7	IO_VREF_L280P_YY	C2 ¹
7	IO_L281N	D2
7	IO_L281P	F5
7	IO_L282N_YY	D3 ⁴
7	IO_L282P_YY	K10 ³
2	CCLK	F26
3	DONE	AJ28
NA	DXN	AJ3
NA	DXP	AH4
NA	M0	AF4
NA	M1	AC7
NA	M2	AK3
NA	PROGRAM	AG28
NA	TCK	B3
NA	TDI	H22
2	TDO	D26
NA	TMS	C1
NA	VCCINT	L11
NA	VCCINT	L12
NA	VCCINT	L19
NA	VCCINT	L20
NA	VCCINT	M11
NA	VCCINT	M12
NA	VCCINT	M19

Table 26: FG900 — XCV600E, XCV1000E, XCV1600E

Bank	Pin Description	Pin #
NA	VCCINT	M20
NA	VCCINT	N13
NA	VCCINT	N14
NA	VCCINT	N15
NA	VCCINT	N16
NA	VCCINT	N17
NA	VCCINT	N18
NA	VCCINT	P13
NA	VCCINT	P18
NA	VCCINT	R13
NA	VCCINT	R18
NA	VCCINT	T13
NA	VCCINT	T18
NA	VCCINT	U13
NA	VCCINT	U18
NA	VCCINT	V13
NA	VCCINT	V14
NA	VCCINT	V15
NA	VCCINT	V16
NA	VCCINT	V17
NA	VCCINT	V18
NA	VCCINT	W11
NA	VCCINT	W12
NA	VCCINT	W19
NA	VCCINT	W20
NA	VCCINT	Y11
NA	VCCINT	Y12
NA	VCCINT	Y19
NA	VCCINT	Y20
NA	VCCO_0	B6
NA	VCCO_0	M15
NA	VCCO_0	M14
NA	VCCO_0	L15
NA	VCCO_0	L14
NA	VCCO_0	H14
NA	VCCO_0	M13

Table 27: FG900 Differential Pin Pair Summary
XCV600E, XCV1000E, XCV1600E

Pair	Bank	P Pin	N Pin	AO	Other Functions
52	1	A22	C21	√	VREF
53	1	B22	H19	4	-
54	1	D22	E21	4	-
55	1	C22	F21	√	VREF
56	1	E22	H20	√	-
57	1	A23	G21	2	-
58	1	K19	A24	2	-
59	1	B24	C24	√	VREF
60	1	G22	H21	√	-
61	1	C25	E23	1	-
62	1	A26	D24	1	-
63	1	K20	B26	√	VREF
64	1	J21	D25	√	-
65	1	F23	C26	2	-
66	1	G23	B27	2	VREF
67	1	F24	A27	2	-
68	1	A28	B28	4	-
69	1	C27	K21	√	CS
70	2	J22	E27	√	DIN, D0
71	2	C29	D28	NA	-
72	2	G25	E25	1	-
73	2	E28	C30	4	VREF
74	2	K22	F27	3	-
75	2	D30	J23	4	-
76	2	L21	F28	1	VREF
77	2	G28	E30	√	-
78	2	G27	E29	4	-
79	2	K23	H26	1	-
80	2	F30	L22	√	VREF
81	2	H27	G29	√	-
82	2	G30	M21	2	-
83	2	J24	J26	4	-
84	2	H30	L23	4	VREF
85	2	K26	J28	4	-

Table 27: FG900 Differential Pin Pair Summary
XCV600E, XCV1000E, XCV1600E

Pair	Bank	P Pin	N Pin	AO	Other Functions
86	2	J29	K24	4	-
87	2	K27	J30	4	VREF
88	2	M22	K29	NA	D2
89	2	K28	L25	4	-
90	2	N21	K25	1	-
91	2	L24	L27	4	-
92	2	L29	M23	3	-
93	2	L26	L28	4	-
94	2	L30	M27	1	VREF
95	2	M26	M29	√	-
96	2	N29	M30	4	-
97	2	N25	N27	1	-
98	2	N30	P21	√	D3
99	2	N26	P28	√	-
100	2	P29	N24	2	-
101	2	P22	R26	√	-
102	2	P25	R29	4	VREF
103	2	R21	R28	4	-
104	2	R25	T30	4	VREF
105	2	P24	R27	4	-
106	3	R24	U29	NA	-
107	3	R22	T27	4	VREF
108	3	R23	T28	4	-
109	3	T21	T25	4	VREF
110	3	U28	U30	4	-
111	3	T23	U27	2	-
112	3	U25	V27	√	-
113	3	U24	V29	√	VREF
114	3	W30	U22	1	-
115	3	U21	W29	4	-
116	3	V26	W27	√	-
117	3	W26	Y29	1	VREF
118	3	W25	Y30	4	-
119	3	V24	Y28	3	-

Table 28: FG1156 — XCV1000E, XCV1600E, XCV2000E, XCV2600E, XCV3200E

Bank	Pin Description	Pin #
0	IO_L40P_Y	A17
0	IO_VREF_L41N_Y	G17 ¹
0	IO_L41P_Y	B17
0	IO_LVDS_DLL_L42N	C17
1	GCK2	D17
1	IO	A18
1	IO	B18 ³
1	IO	B24
1	IO	B25
1	IO	E22 ³
1	IO	E23 ³
1	IO	D18 ³
1	IO	D19
1	IO	D25 ³
1	IO	D26 ³
1	IO	D28 ³
1	IO	D29 ³
1	IO	G23 ³
1	IO	J23 ³
1	IO_LVDS_DLL_L42P	J18
1	IO_L43N_Y	G18
1	IO_VREF_L43P_Y	C18 ¹
1	IO_L44N_Y	H18
1	IO_L44P_Y	F18
1	IO_L45N_YY	B19
1	IO_VREF_L45P_YY	A19
1	IO_L46N_YY	K19
1	IO_L46P_YY	C19
1	IO_L47N	F19 ⁵
1	IO_L47P	E19 ⁴
1	IO_L48N_Y	G19
1	IO_L48P_Y	J19
1	IO_L49N_Y	A20

Table 28: FG1156 — XCV1000E, XCV1600E, XCV2000E, XCV2600E, XCV3200E

Bank	Pin Description	Pin #
1	IO_L49P_Y	G20
1	IO_L50N	B20 ⁵
1	IO_L50P	F20 ⁴
1	IO_L51N_YY	D20
1	IO_VREF_L51P_YY	E20
1	IO_L52N_YY	H20
1	IO_L52P_YY	A21
1	IO_L53N	E21 ⁵
1	IO_L53P	J20 ⁴
1	IO_L54N_Y	D21
1	IO_L54P_Y	K20
1	IO_L55N_Y	B21
1	IO_L55P_Y	H21
1	IO_L56N_YY	G21 ⁵
1	IO_L56P_YY	F21 ⁴
1	IO_L57N_YY	A22
1	IO_VREF_L57P_YY	B22
1	IO_L58N_YY	J21
1	IO_L58P_YY	C22
1	IO_L59N_Y	D22
1	IO_L59P_Y	G22
1	IO_L60N_Y	K21
1	IO_L60P_Y	A23
1	IO_L61N_Y	F22
1	IO_L61P_Y	B23
1	IO_L62N_Y	C23
1	IO_L62P_Y	H22
1	IO_L63N_YY	D23
1	IO_L63P_YY	K22
1	IO_L64N_YY	A24
1	IO_VREF_L64P_YY	J22
1	IO_L65N_Y	H23
1	IO_L65P_Y	D24
1	IO_L66N_Y	A25

Table 28: FG1156 — XCV1000E, XCV1600E, XCV2000E, XCV2600E, XCV3200E

Bank	Pin Description	Pin #
1	IO_L66P_Y	E24
1	IO_L67N_YY	A26
1	IO_VREF_L67P_YY	C25
1	IO_L68N_YY	F24
1	IO_L68P_YY	B26
1	IO_L69N	K23 ⁵
1	IO_L69P	F25 ⁴
1	IO_L70N_Y	C26
1	IO_VREF_L70P_Y	H24 ²
1	IO_L71N_Y	G24
1	IO_L71P_Y	A27
1	IO_L72N	B27 ⁵
1	IO_L72P	G25 ⁴
1	IO_L73N_YY	E26
1	IO_VREF_L73P_YY	C27
1	IO_L74N_YY	J24
1	IO_L74P_YY	B28
1	IO_L75N	K24 ⁵
1	IO_L75P	H25 ⁴
1	IO_L76N_Y	D27
1	IO_L76P_Y	F26
1	IO_L77N_Y	G26
1	IO_L77P_Y	C28
1	IO_L78N_YY	E27 ⁵
1	IO_L78P_YY	J25 ⁴
1	IO_L79N_YY	A30
1	IO_VREF_L79P_YY	H26
1	IO_L80N_YY	G27
1	IO_L80P_YY	B29
1	IO_L81N_Y	F27
1	IO_L81P_Y	C29
1	IO_L82N_Y	E28
1	IO_VREF_L82P_Y	F28
1	IO_L83N_Y	L25

Table 28: FG1156 — XCV1000E, XCV1600E, XCV2000E, XCV2600E, XCV3200E

Bank	Pin Description	Pin #
1	IO_L83P_Y	B30
1	IO_L84N	B31
1	IO_L84P	E29
1	IO_WRITE_L85N_YY	A31
1	IO_CS_L85P_YY	D30
2	IO	F31 ³
2	IO	J32
2	IO	K27 ³
2	IO	K31 ³
2	IO	L28 ³
2	IO	L30 ³
2	IO	M32 ³
2	IO	N26
2	IO	N28 ³
2	IO	P25 ³
2	IO	U26 ³
2	IO	U30
2	IO	U32 ³
2	IO	U34
2	IO_D2	M30
2	IO_DOUT_BUSY_L86P_YY	D32
2	IO_DIN_D0_L86N_YY	J27
2	IO_L87P_Y	E31
2	IO_L87N_Y	F30
2	IO_L88P_Y	G29
2	IO_L88N_Y	F32
2	IO_VREF_L89P_Y	E32
2	IO_L89N_Y	G30
2	IO_L90P	M25
2	IO_L90N	G31
2	IO_L91P_Y	L26
2	IO_L91N_Y	D33
2	IO_VREF_L92P_Y	D34

Table 28: FG1156 — XCV1000E, XCV1600E, XCV2000E, XCV2600E, XCV3200E

Bank	Pin Description	Pin #
4	IO_L212N_YY	AP18
4	IO_L213P_Y	AF18
4	IO_L213N_Y	AP17
4	IO_VREF_L214P_Y	AJ18 ¹
4	IO_L214N_Y	AL18
4	IO_LVDS_DLL_L215P	AM18
5	GCK1	AL19
5	IO	AF17 ³
5	IO	AG12 ³
5	IO	AH12
5	IO	AJ10 ³
5	IO	AJ11 ³
5	IO	AK7 ³
5	IO	AK13 ³
5	IO	AL13 ³
5	IO	AM4 ³
5	IO	AN9
5	IO	AN10 ³
5	IO	AN16
5	IO	AN17 ³
5	IO_LVDS_DLL_L215N	AL17
5	IO_L216P_Y	AH17
5	IO_VREF_L216N_Y	AM17 ¹
5	IO_L217P_Y	AJ17
5	IO_L217N_Y	AG17
5	IO_L218P_YY	AP16
5	IO_VREF_L218N_YY	AL16
5	IO_L219P_YY	AJ16
5	IO_L219N_YY	AM16
5	IO_L220P	AK16 ⁵
5	IO_L220N	AP15 ⁴
5	IO_L221P_Y	AL15
5	IO_L221N_Y	AH16

Table 28: FG1156 — XCV1000E, XCV1600E, XCV2000E, XCV2600E, XCV3200E

Bank	Pin Description	Pin #
5	IO_L222P_Y	AN15
5	IO_L222N_Y	AF16
5	IO_L223P_Y	AP14 ⁵
5	IO_L223N_Y	AE16 ⁴
5	IO_L224P_YY	AK15
5	IO_VREF_L224N_YY	AJ15
5	IO_L225P_YY	AH15
5	IO_L225N_YY	AN14
5	IO_L226P	AK14 ⁵
5	IO_L226N	AG15 ⁴
5	IO_L227P_Y	AM13
5	IO_L227N_Y	AF15
5	IO_L228P_Y	AG14
5	IO_L228N_Y	AP13
5	IO_L229P_YY	AE14 ⁵
5	IO_L229N_YY	AE15 ⁴
5	IO_L230P_YY	AN13
5	IO_VREF_L230N_YY	AG13
5	IO_L231P_YY	AH14
5	IO_L231N_YY	AP12
5	IO_L232P_Y	AJ14
5	IO_L232N_Y	AL14
5	IO_L233P_Y	AF13
5	IO_L233N_Y	AN12
5	IO_L234P_Y	AF14
5	IO_L234N_Y	AP11
5	IO_L235P_Y	AN11
5	IO_L235N_Y	AH13
5	IO_L236P_YY	AM12
5	IO_L236N_YY	AL12
5	IO_L237P_YY	AJ13
5	IO_VREF_L237N_YY	AP10
5	IO_L238P_Y	AK12
5	IO_L238N_Y	AM10